



Technical Data Sheet

Lead free Solder Paste F 620 Series

Description	F 620 Solder Paste series is a state-of-the-art lead free no clean solder paste that promotes wetting and minimises soldering defects. The F 620 flux system is specifically optimised for Sn/Ag/Cu alloy soldering. Extensive testing at customer locations has proven this paste to be capable of defect-free performance in the production environment. The F 620 Series exhibits minimal slump and has excellent print-after-wait performance.																																																																				
Key Benefits	<ul style="list-style-type: none"> - Outstanding wetting - Exceptional print to print consistency - Min. 8 hours tack and work life 			Compliant Products																																																																	
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Flux Activity	No Clean <input checked="" type="checkbox"/>	Water Washable <input type="checkbox"/>	ISO 9454-1:1990 [DIN EN 29454-1:1993] 1.2.2.C	J-STD-004A:2004 RELO	Belcore GR-78-Core [Issue 1:1997] not tested	Siemens Norm [SN 59650:1998] not tested																																																															
Halogen Content	Halogen Free <input type="checkbox"/> <small>Halogen Free-Tolerances from IEC 61249-2-21: Cl or Br <900ppm, total <1500ppm; measured according to BS EN 14582</small>			Halogen Zero - No Halogen added in the Flux: <input type="checkbox"/> <small>Halogen Zero - Tolerance: Halogen < 50 ppm; measured according to BS EN 14582</small>																																																																	
Paste Conditioning	Remove paste from fridge: Before opening the package leave paste 2 hours at room temperature so that paste warms up. Do not open jar/cartridge while paste is cold to prevent condensation of moisture on the paste - this causes defects, e.g. solder balling etc. Do not heat the paste. Before use of paste jar: To obtain uniform, stable viscosity stir paste for 1 to 2 min, using a stainless steel or chemically resistive plastic spatula. For further Information see Technical Information.																																																																				
Reflow	Temperature profile adjustment according IPC/JEDEC J-STD-020.																																																																				
Cleaning	After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.																																																																				
Storage	Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity. Max expiration date: please refer to the expiry date on the label of the packaged product. Storage conditions in the refrigerator at 2-10°C.																																																																				
Contact	www.heraeus-contactmaterials.com			Version	TDS_Solder Paste F620 Series_18.March 2015																																																																

The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application